SCCS038B - SEPTEMBER 1994 - REVISED OCTOBER 2001

- Function and Pinout Compatible With FCT and F Logic
- 25-Ω Output Series Resistors to Reduce Transmission-Line Reflection Noise
- TTL Output Level Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Fully Compatible With TTL Input and Output Logic Levels
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- 12-mA Output Sink Current
 15-mA Output Source Current
- 3-State Outputs

Q OR SO PACKAGE (TOP VIEW) S V_{CC} 16 15 OE I_{0a} I_{1a} [14 🛮 I_{0c} Y_a 13 I I_{1c} 12 Y_C I_{0b} [11 🛮 I_{0d} I_{1b} Y_b [7 10 🛮 I_{1d} 9]] Y_d GND ∏8

description

The CY74FCT2257T has four identical two-input multiplexers that select four bits of data from two sources under the control of a common data-select (S) input. The I_0 inputs are selected when S is low, and the I_1 inputs are selected when S is high. Data appears at the output in noninverted form for the CY74FCT2257T. On-chip termination resistors at the outputs reduce system noise caused by reflections. The CY74FCT2257T can replace the FCT257T to reduce noise in an existing design.

The CY74FCT2257T is a logic implementation of a four-pole, two-position switch, in which the position of the switch is determined by the logic levels supplied to S. Outputs are forced to the high-impedance off state when the output-enable (\overline{OE}) input is high.

All but one device must be in the high-impedance state to prevent currents from exceeding the maximum ratings if outputs are tied together. Design of the \overline{OE} signals must ensure that there is no overlap when outputs of 3-state devices are tied together.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

PIN DESCRIPTION

NAME	DESCRIPTION
I	Data inputs
S	Common data-select input
OE	Output-enable input (active low)
Υ	Data outputs



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ORDERING INFORMATION

TA	PAC	(AGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	QSOP - Q	Tape and reel	4.3	CY74FCT2257CTQCT	FR257-3	
-40°C to 85°C	SOIC - SO	Tube	4.3	CY74FCT2257CTSOC	FCT2257C	
-40 C to 85 C	3010 - 30	Tape and reel	4.3	CY74FCT2257CTSOCT	10122370	
	QSOP - Q	Tape and reel	5	CY74FCT2257ATQCT	FR257-1	

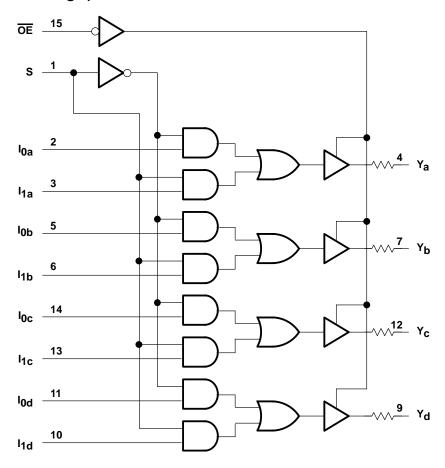
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS									
OE	S	I ₀	l ₁	Y						
Н	Х	Х	Х	Z						
L	Н	X	L	L						
L	Н	Χ	Н	Н						
L	L	L	X	L						
L	L	Н	Χ	Н						

H = High logic level, L = Low logic level, X = Don't care, Z = High-impedance (off) state

logic diagram (positive logic)





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absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	0.5 V to 7 V
DC input voltage range	0.5 V to 7 V
DC output voltage range	0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): Q package	90°C/W
SO package .	57°C/W
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			8.0	V
ІОН	High-level output current			-15	mA
loL	Low-level output current			12	mA
TA	Operating free-air temperature	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION	S	MIN	TYP	MAX	UNIT
VIK	V _{CC} = 4.75 V,	$I_{IN} = -18 \text{ mA}$			-0.7	-1.2	V
V _{OH}	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -15 \text{ mA}$		2.4	3.3		V
V _{OL}	$V_{CC} = 4.75 \text{ V},$	I _{OL} = 12 mA			0.3	0.55	V
R _{out}	V _{CC} = 4.75 V,	I _{OL} = 12 mA		20	25	40	Ω
V_{hys}	All inputs				0.2		V
lН	$V_{CC} = 5.25 \text{ V},$	V _{IN} = 2.7 V				±1	μΑ
IĮL	$V_{CC} = 5.25 \text{ V},$	$V_{IN} = 0.5 V$				±1	μΑ
^I OZH	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 2.7 V				10	μΑ
l _{OZL}	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0.5 V				-10	μΑ
los [‡]	$V_{CC} = 5.25 \text{ V},$	VOUT = 0 V		-60	-120	-225	mA
l _{off}	$V_{CC} = 0 V$,	V _{OUT} = 4.5 V				±1	μΑ
lcc	$V_{CC} = 5.25 \text{ V},$	$V_{IN} \le 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2	mA
∆ICC	V _{CC} = 5.25 V, V _{IN} =	: 3.4 V\$, f ₁ = 0, Outputs or	oen		0.5	2	mA
ICCD¶	$\frac{\text{V}_{CC}}{\text{OE}} = 5.25 \text{ V, One in OE} = \text{GND, V}_{IN} \le 0.25 \text{ C}$	nput switching at 50% duty 2 V or $V_{IN} \ge V_{CC} - 0.2 V$	y cycle, Outputs open,		0.06	0.12	mA/ MHz
		One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4	
lc#	V _{CC} = 5.25 V,	at 50% duty cycle	V _{IN} = 3.4 V or GND		1	2.4	mA
ı.C.,	$I_{\mathbb{C}}^{\#}$ Outputs open, $\overline{OE} = GND$	Four bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4	IIIA
		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1.7	5.4	
Ci					5	10	pF
Co					9	12	pF

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

Where:

IC = Total supply current

ICC = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

ICCD = Dynamic current caused by an input transition pair (HLH or LHL)

f₀ = Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

N₁ = Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

[§] Per TTL-driven input (VIN = 3.4 V); all other inputs at VCC or GND

This parameter is derived for use in total power-supply calculations.

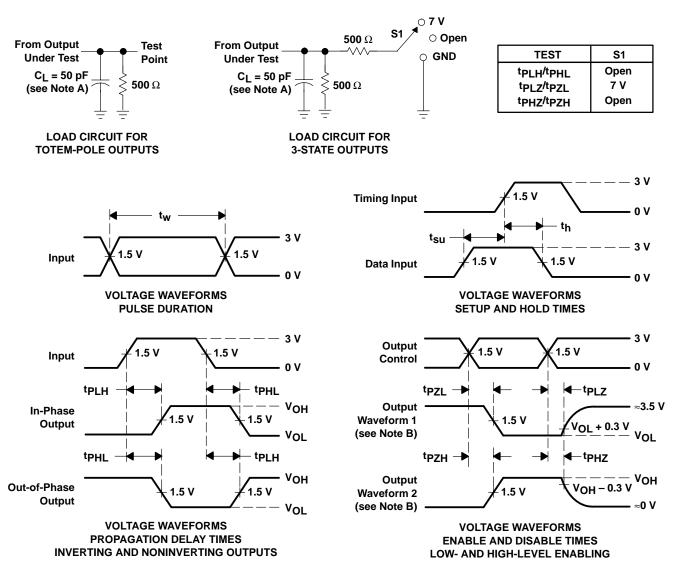
 $^{^{\#}}$ IC = ICC + Δ ICC \times DH \times NT + ICCD (f₀/2 + f₁ \times N₁)

CY74FCT2257T QUAD 2-INPUT MULTIPLEXER WITH 3-STATE OUTPUTS SCCS038B - SEPTEMBER 1994 - REVISED OCTOBER 2001

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FCT2	2257AT	CY74FCT2	2257CT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
^t PLH	Lorb	V	1.5	5	1.5	4.7	ns
^t PHL	l _a or l _b	ı	1.5	5	1.5	4.7	115
^t PLH	S	V	1.5	7	1.5	5.2	nc
^t PHL	3	ı	1.5	7	1.5	5.2	ns
^t PZH	-	V	1.5	7	1.5	6	ns
t _{PZL}	ŌĒ	ī	1.5	7	1.5	6	115
^t PHZ	ŌĒ	٧	1.5	5.5	1.5	5	ns
^t PLZ	OE .	1	1.5	5.5	1.5	5	115

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CY74FCT2257ATQCT	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FR257-1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT2257ATQCT	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT2257ATQCT	SSOP	DBQ	16	2500	340.5	338.1	20.6



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



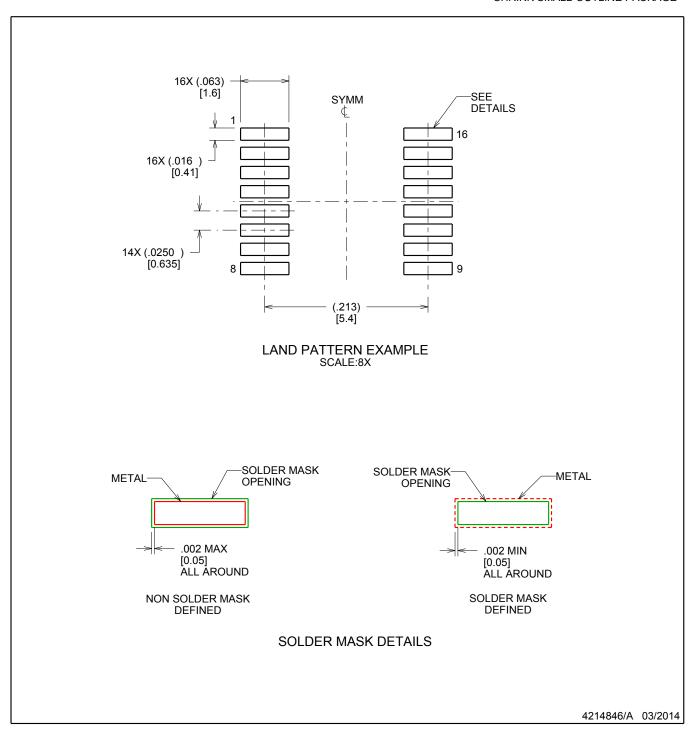




NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 inch, per side.
- 4. This dimension does not include interlead flash.5. Reference JEDEC registration MO-137, variation AB.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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